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5/28/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 09/825,664
Filing Date April 3, 2001
Inventor David R. Hembree
Assignee Micron Technology, Inc.
Group Art Unit 2858
Examiner V. Nguyen
Attorney's Docket No. MI22-1680
Title: Electronic Device Wafer Processing Members and Wafer Processing Apparatuses

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

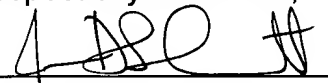
References -- See Attached Form PTO-1449

The attached form PTO-1449 is submitted in compliance with 37 CFR §1.56. No admission is made regarding whether all the submitted references are prior art.

Dated: 5/10/02

Attorney:

Respectfully submitted,


James D. Shaurette
Reg. No. 39,833

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U.S. PATENT DOCUMENTS

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	5,886,863	3/23/1999	Nagasaki et al.			
	AB						
	AC						
	AD						

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

	AE		
	AF		
	AG		
	AH		
	AI		
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	AK		
	AL		

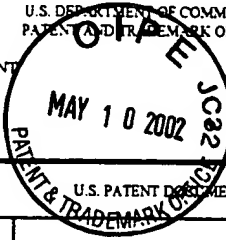
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Form PTO-1449

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U.S. PATENT DOCUMENTS

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	3,440,407	4/22/69	Golstos et al.			
	AB	3,614,345	10/19/71	Quinn			
	AC	3,683,306	8/8/72	Buthaus et al.			
	AD	4,332,081	6/1/82	Francis			
	AE	4,518,944	5/21/85	Faris			
	AF	4,703,555	11/3/87	Hubner			
	AG	5,141,334	8/25/92	Castles			
	AH	5,347,869	9/20/94	Shie et al.			
	AI	5,406,109	4/11/95	Whitney			
	AJ	5,436,646	7/25/95	McArthur et al.			
	AK	5,446,437	8/29/95	Bantien et al.			

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
	AL	2336778	7/1977	France				
	AM	56-12521	2/1981	Kobayashi, Japan				
	AN	2-268462	11-1990	Yamanishi, Japan				
	AO							
	AP							

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

	AR	✓	Application Guide Temperature Sensors, Watlow Electrical Manufacturing Company Catalog, pp. 773-778, 1992/1993.
	AS	✓	In-Situ survey System of Resistive and Thermoelectric Properties of Either Pure or Mixed Materials in Thin Films Evaporated Under Ultra High Vacuum, LeChevallier, LeHueron, Richon, Serru, & Goumih, J. Phys. III France, Vol. 5, pp. 409-418, 04/95 (Abstract only).
	AT	✓	Temperature Metrology for CD Control in DUV Lithography, Jeffrey Parker and Wayne Resken, pp. 111-112, 114, 116, 09/17/97.

EXAMINER

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Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE <div style="border: 2px solid black; border-radius: 50%; width: 100px; height: 100px; display: flex; align-items: center; justify-content: center; margin: 0 auto;"> <div style="writing-mode: vertical-rl; transform: rotate(180deg); font-weight: bold;">RECEIVED</div> <div style="text-align: center;"> MAY 10 2002 PATENT & TRADEMARK OFFICE </div> </div>			ATTY. DOCKET NO. M122-1680	SERIAL NO. 09/825,664
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)						
APPLICANT David Hembree			FILING DATE April 3, 2001			
			GROUP 2858			
FOREIGN PATENT DOCUMENTS						
*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	5,612,574	3/18/97	Summerfelt et al.		
	AB	5,719,333	2/17/98	Hosoi et al.		
	AC	5,831,333	11/3/98	Malladi et al.		
	AD	5,919,548	7/6/99	Barron et al.		
	AE	5,551,283	9/3/96	Manaka et al.		
	AF	5,492,011	2/20/96	Amano et al.		
	AG					
	AH					
	AJ					
FOREIGN PATENT DOCUMENTS						
	Document Number	Date	Country	Class	Subclass	Translation
						Yes No
	AK					
	AL					
	AM					
	AN					
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)						
	AP	"NTC and PTC Thermistors"; http://www.thermodisc.com/ntcptc.html ; 1/7/98; 2 pages.				
	AR	"DI-SB35 Linearized 4-Wire RTD Input"; http://www.dataq.com/di5b35.html ; 1/7/98; 2 pages.				
	AS	"RTD"; http://www.mtisensors.com/rtds.html ; 1/7/98; 3 pages.				
	AT	"Low Cost Thermal-Ribbon (TM) uses thin film RTD"; http://www.minco.com/sl7624nr.html ; 1/7/98; 1 page.				
	AU	"Silicon Processing for the VLSI Era"; Volume 1 - Process Technology, Second Edition; S. Wolf et al.; 2000; pps 22-25 and pps. 841-845.				
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